COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET
POWERDI®5060-8

Product Summary

Device	$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D T_A = +25°C
Q1	12V	17mΩ @ V_{GS} = 4.5V	9.5A
		25mΩ @ V_{GS} = 2.5V	7.8A
Q2	-12V	32mΩ @ V_{GS} = -4.5V	-6.9A
		53mΩ @ V_{GS} = -2.5V	-5.4A

Features and Benefits

- Thermally Efficient Package-Cooler Running Applications
- High Conversion Efficiency
- Low $R_{DS(ON)}$ – Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

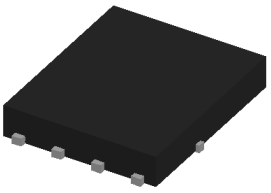
Description and Applications

This new generation Complementary Pair Enhancement Mode MOSFET has been designed to minimize $R_{DS(on)}$ and yet maintain superior switching performance. This device is ideal for use in Notebook battery power management and Loadswitch.

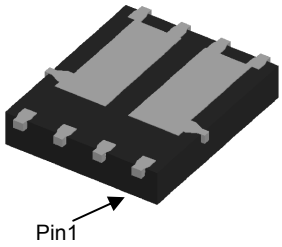
- Notebook Battery Power Management
- DC-DC Converters
- Loadswitch

Mechanical Data

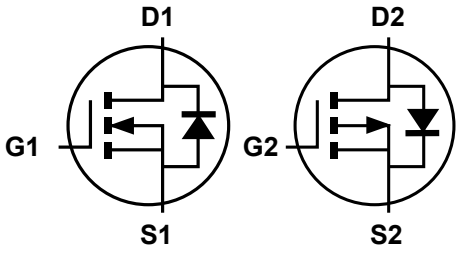
- Case: POWERDI5060-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Weight: 0.097 grams (approximate)



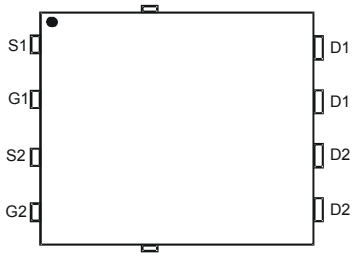
Top View



Bottom View



Q1 N-Channel MOSFET Q2 P-Channel MOSFET



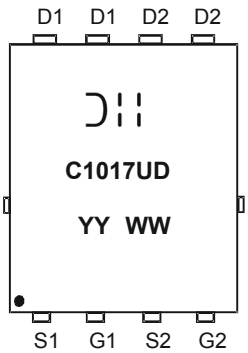
Top View
Pin Configuration

Ordering Information (Note 4)

Part Number	Case	Packaging
DMC1017UPD-13	POWERDI5060-8	2500 / Tape & Reel

Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



Ↄ¦¦ = Manufacturer's Marking
C1017UD = Product Type Marking Code
YYWW = Date Code Marking
YY = Year (ex: 13 = 2013)
WW = Week (01 - 53)

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Q1 Value	Q2 Value	Units
Drain-Source Voltage			V_{DSS}	12	-12	V
Gate-Source Voltage			V_{GSS}	±8	±8	V
Continuous Drain Current (Note 5) V_{GS} = 4.5V	Steady State	T_A = +25°C T_A = +70°C	I_D	9.5 7.6	-6.9 -5.5	A
	t<10s	T_A = +25°C T_A = +70°C	I_D	13.0 10.4	-9.4 -7.5	A
Maximum Body Diode Forward Current			I_S	2	-2	A
Pulsed Drain Current (10µs pulse, duty cycle = 1%)			I_{DM}	50	-35	A
Avalanche Current (Note 6) L = 0.1mH			I_{AS}	9.7	-9.2	A
Avalanche Energy (Note 6) L = 0.1mH			E_{AS}	4.7	4.3	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	T_A = +25°C	P_D	2.3	W
	T_A = +70°C		1.5	
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	$R_{\theta JA}$	54	°C/W
	t<10s		29	
Thermal Resistance, Junction to Case (Note 5)		$R_{\theta JC}$	4.1	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics Q1 N-Channel (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	12	—	—	V	V_{GS} = 0V, I_D = 250µA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	µA	V_{DS} = 12V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±100	nA	V_{GS} = ±8V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(th)}$	0.6	—	1.5	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	9.6	17	mΩ	V_{GS} = 4.5V, I_D = 11.8A
		—	11	25		V_{GS} = 2.5V, I_D = 9.8A
Diode Forward Voltage	V_{SD}	—	0.7	1.2	V	V_{GS} = 0V, I_S = 2.9A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	1787	—	pF	V_{DS} = 6V, V_{GS} = 0V, f = 1.0MHz
Output Capacitance	C_{oss}	—	297	—		
Reverse Transfer Capacitance	C_{rss}	—	265	—		
Gate Resistance	R_G	—	1.6	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz
Total Gate Charge (V_{GS} = 4.5V)	Q_g	—	18.6	—	nC	V_{DS} = 6V, I_D = 11.8A
Total Gate Charge (V_{GS} = 10V)	Q_g	—	35.4	—		
Gate-Source Charge	Q_{gs}	—	2.7	—		
Gate-Drain Charge	Q_{gd}	—	3.8	—		
Turn-On Delay Time	$t_{D(on)}$	—	6.9	—	nS	V_{DD} = 6V, R_L = 6Ω V_{GS} = 4.5V, R_G = 6Ω, I_D = 1A
Turn-On Rise Time	t_r	—	10.9	—		
Turn-Off Delay Time	$t_{D(off)}$	—	70.3	—		
Turn-Off Fall Time	t_f	—	31.8	—		
Body Diode Reverse Recovery Time	t_{rr}	—	13.1	—	nS	I_F = 11.8A, di/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q_{rr}	—	2.2	—	nC	I_F = 11.8A, di/dt = 100A/µs

Notes:
5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
6. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep T_J = 25°C.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.

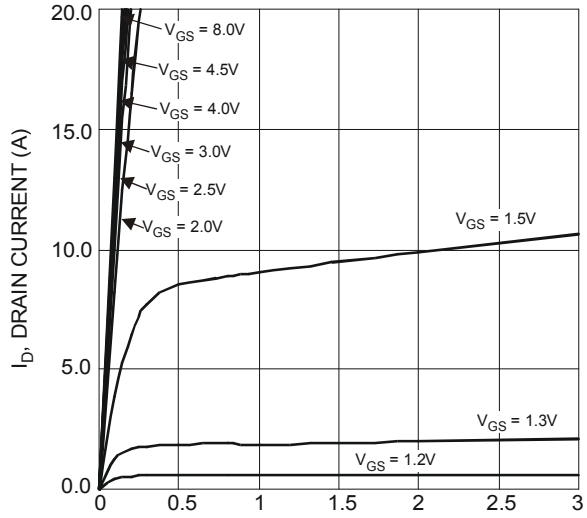


Figure 1 Typical Output Characteristics

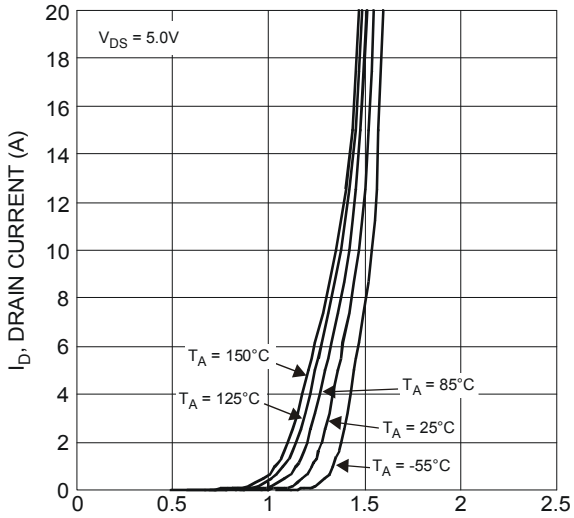


Figure 2 Typical Transfer Characteristics

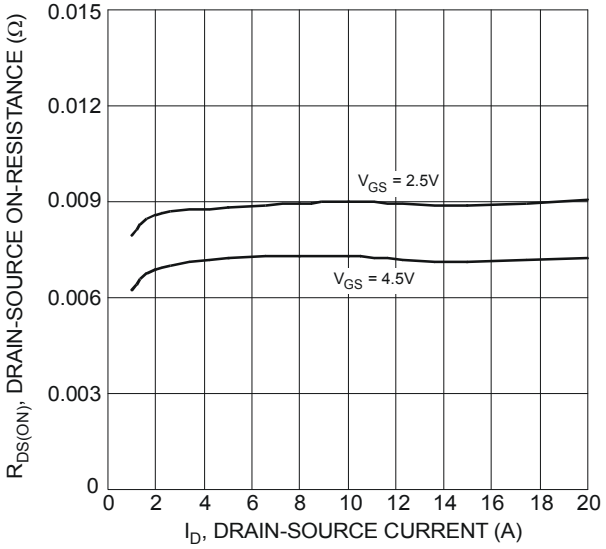


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

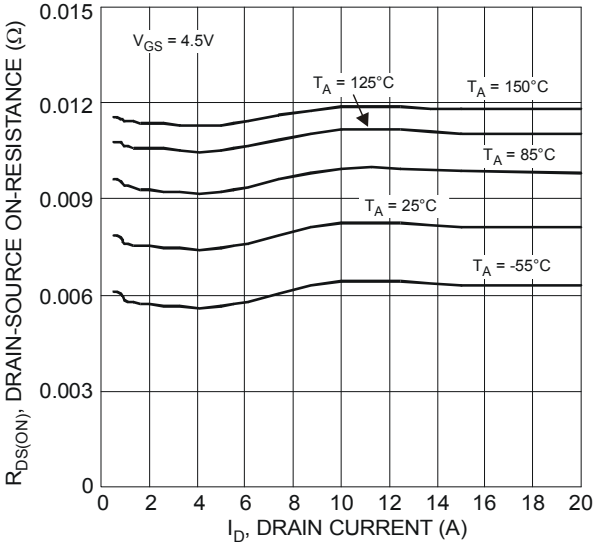


Figure 4 Typical On-Resistance vs. Drain Current and Temperature

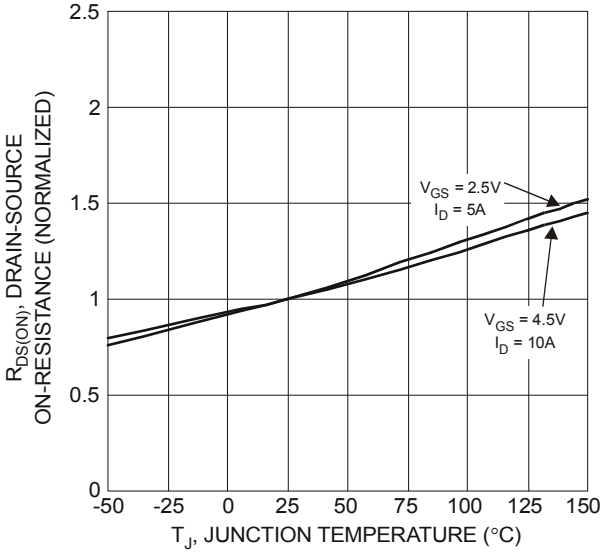


Figure 5 On-Resistance Variation with Temperature

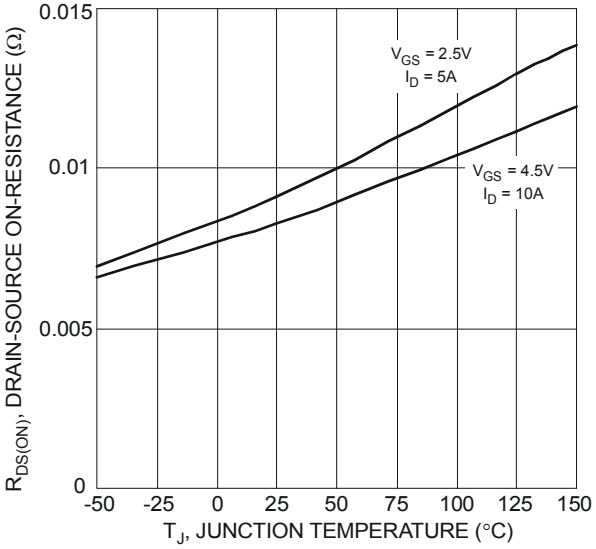


Figure 6 On-Resistance Variation with Temperature

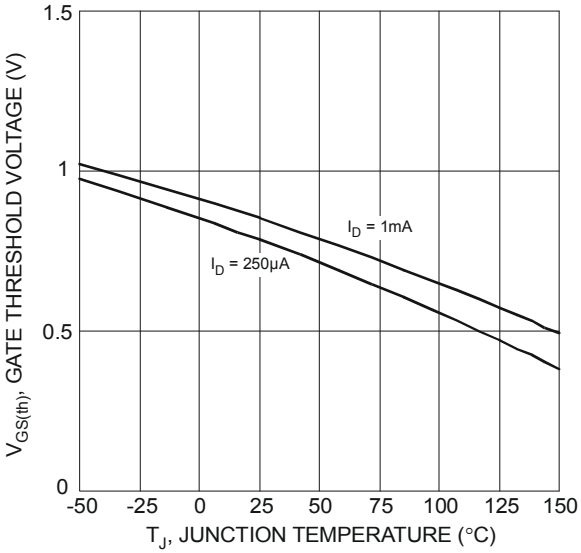


Figure 7 Gate Threshold Variation vs. Ambient Temperature

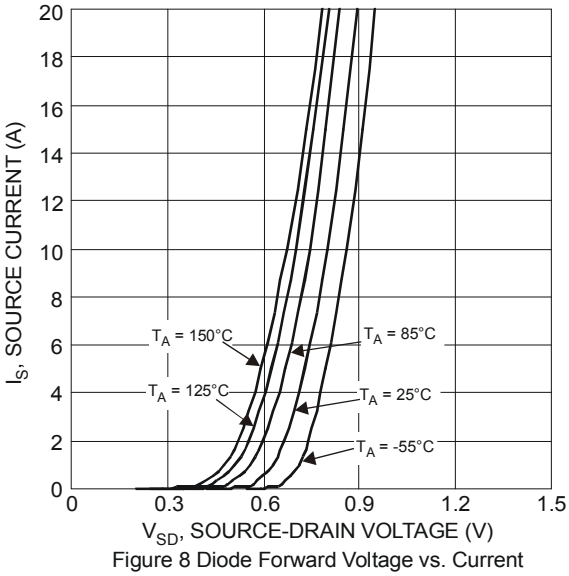


Figure 8 Diode Forward Voltage vs. Current

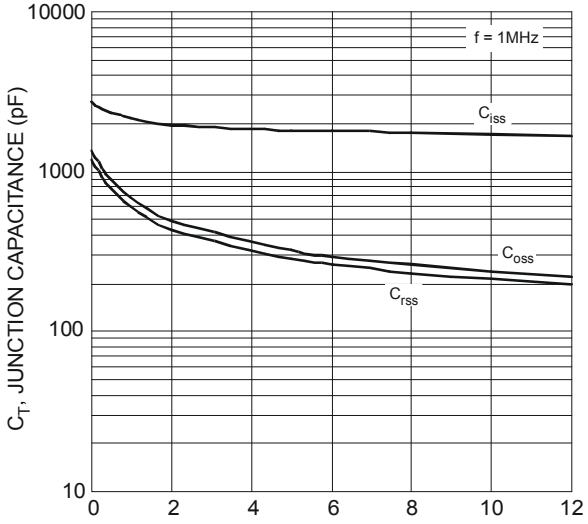


Figure 9 Typical Junction Capacitance

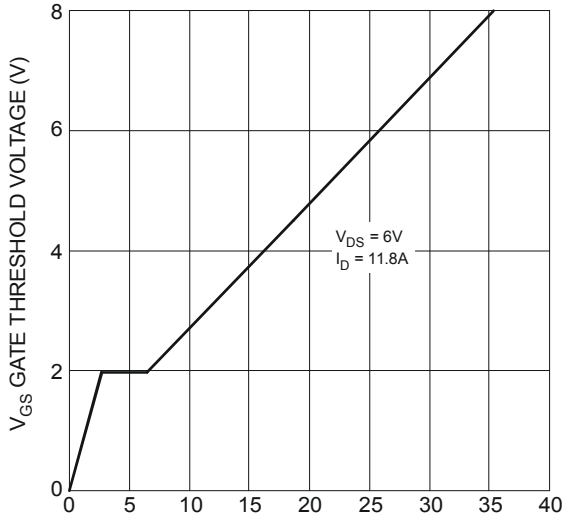


Figure 10 Gate Charge

Electrical Characteristics Q2 P-Channel (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BV_{DSS}	-12	—	—	V	V_{GS} = 0V, I_D = -250μA
Zero Gate Voltage Drain Current	I_{DSS}	—	—	-1	μA	V_{DS} = -12V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±100	nA	V_{GS} = ±8V, V_{DS} = 0V
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	$V_{GS(th)}$	-0.6	—	-1.5	V	V_{DS} = V_{GS}, I_D = -250μA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	21	32	mΩ	V_{GS} = -4.5V, I_D = -8.9A
		—	41	53		V_{GS} = -2.5V, I_D = -6.9A
Diode Forward Voltage	V_{SD}	—	-0.7	-1.2	V	V_{GS} = 0V, I_S = -2.9A
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	C_{iss}	—	2100	—	pF	V_{DS} = -6V, V_{GS} = 0V, f = 1.0MHz
Output Capacitance	C_{oss}	—	872	—		
Reverse Transfer Capacitance	C_{rss}	—	626	—		
Gate Resistance	R_G	—	23.1	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz
Total Gate Charge (V_{GS} = -4.5V)	Q_g	—	23.7	—	nC	V_{DS} = -6V, I_D = -8.9A
Total Gate Charge (V_{GS} = -8V)	Q_g	—	38.8	—		
Gate-Source Charge	Q_{gs}	—	5.3	—		
Gate-Drain Charge	Q_{gd}	—	9.8	—		
Turn-On Delay Time	$t_{D(on)}$	—	10.6	—	nS	V_{DD} = -6V, R_L = 6Ω, V_{GS} = -4.5V, R_G = 6Ω, I_D = -1A
Turn-On Rise Time	t_r	—	25.5	—		
Turn-Off Delay Time	$t_{D(off)}$	—	144	—		
Turn-Off Fall Time	t_f	—	129	—		
Body Diode Reverse Recovery Time	t_{rr}	—	48.9	—	nS	I_F = -8.9A, di/dt = -100A/μs
Body Diode Reverse Recovery Charge	Q_{rr}	—	15.3	—	nC	I_F = -8.9A, di/dt = -100A/μs

Notes: 6. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep T_J = 25°C.
7. Short duration pulse test used to minimize self-heating effect.

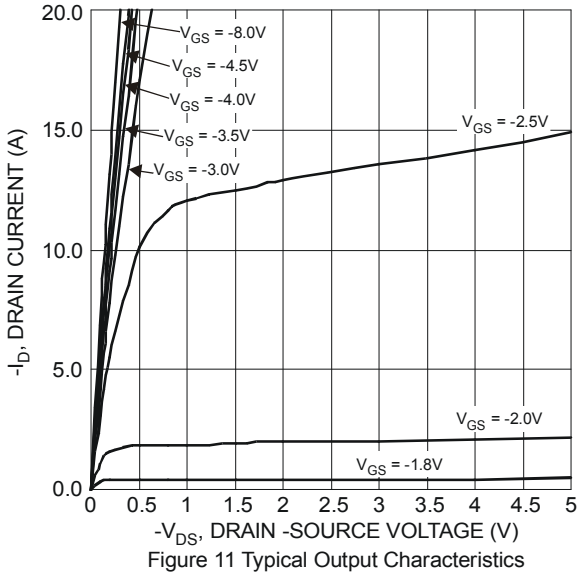


Figure 11 Typical Output Characteristics

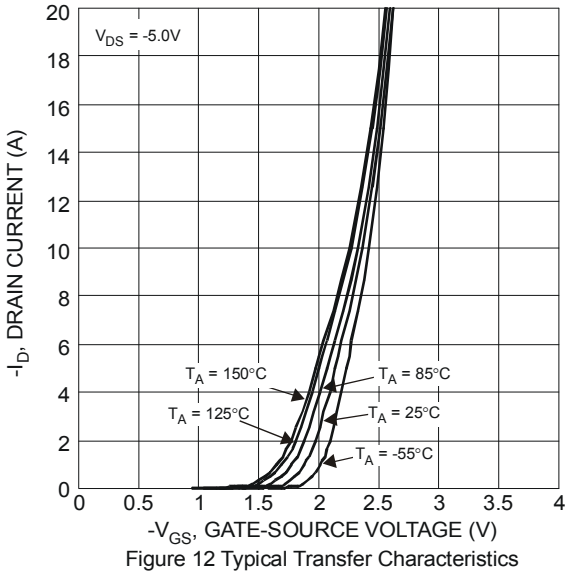


Figure 12 Typical Transfer Characteristics

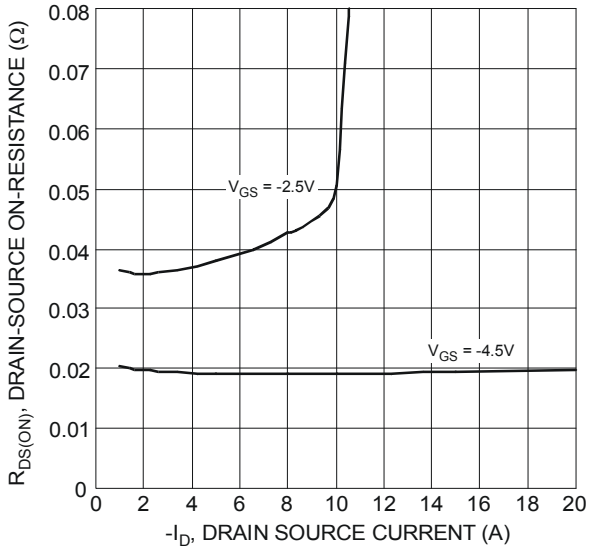


Figure 13Typical On-Resistance vs. Drain Current and Gate Voltage

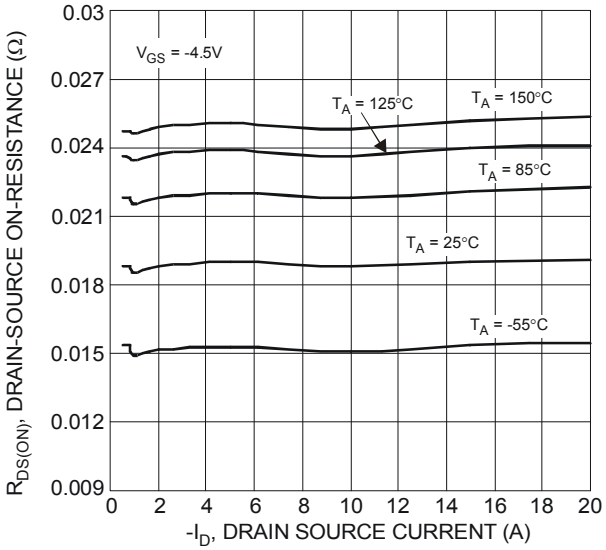


Figure 14 Typical On-Resistance vs. Drain Current and Temperature

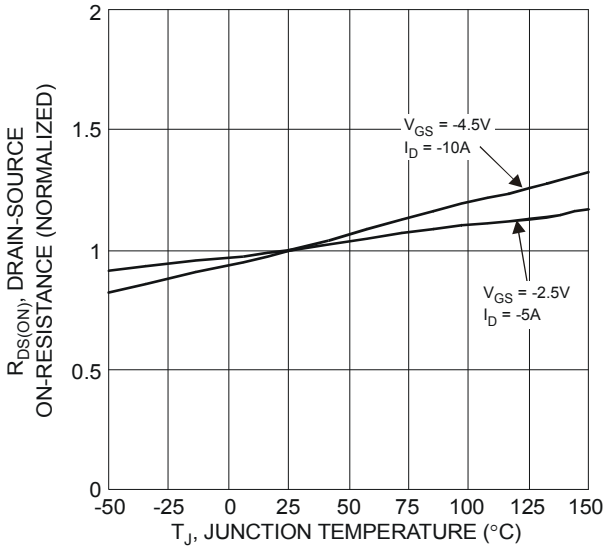


Figure 15 On-Resistance Variation with Temperature

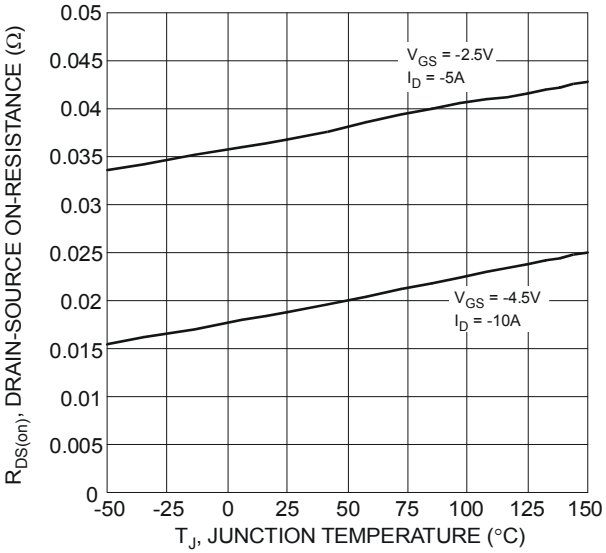


Figure 16 On-Resistance Variation with Temperature

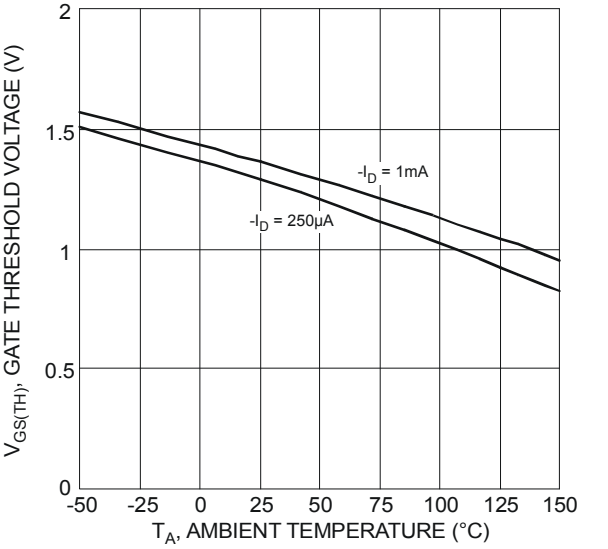


Figure 17 Gate Threshold Variation vs. Ambient Temperature

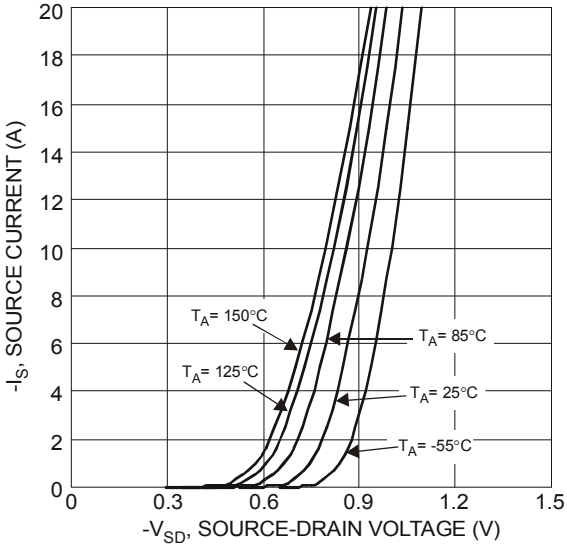


Figure 18 Diode Forward Voltage vs. Current

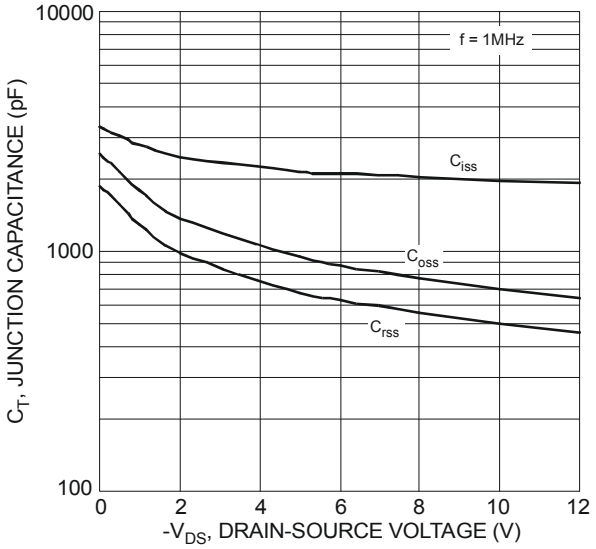


Figure 19 Typical Junction Capacitance

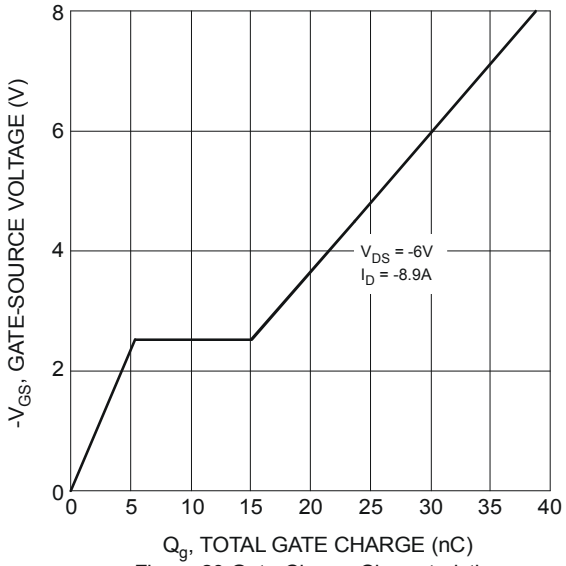


Figure 20 Gate-Charge Characteristics

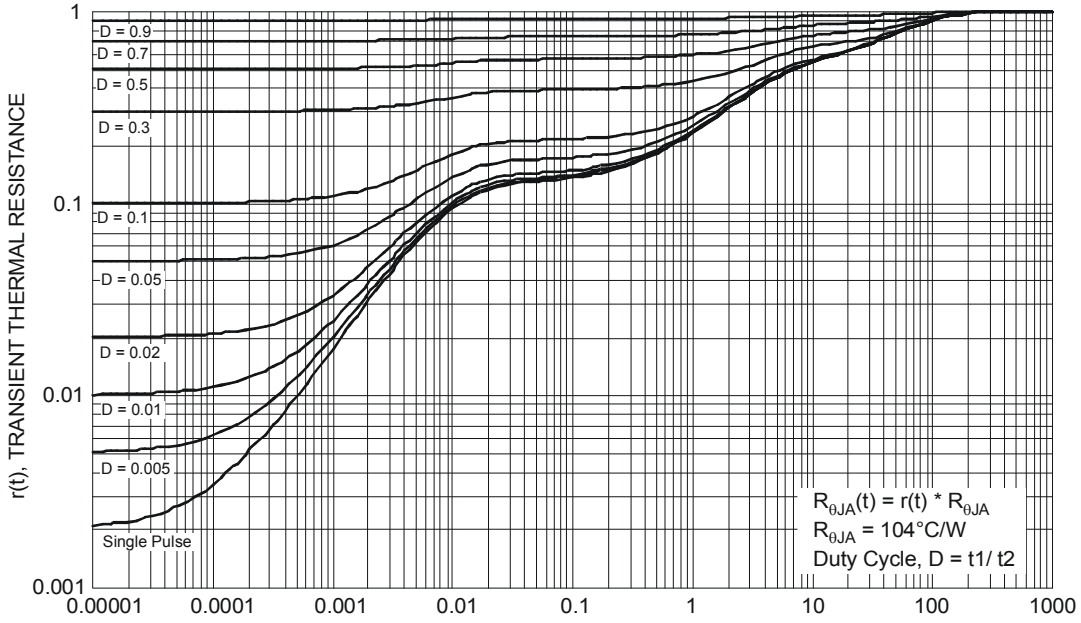
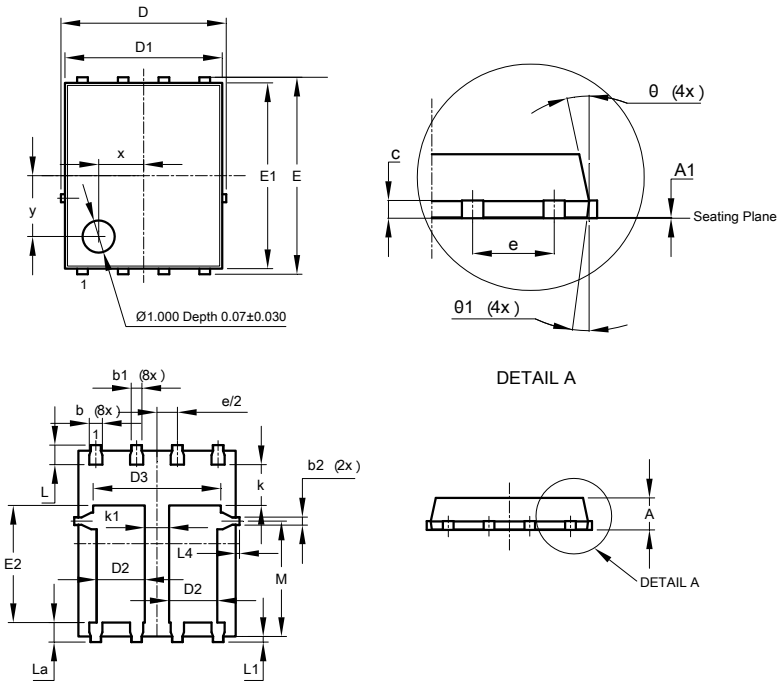


Figure 21 Transient Thermal Resistance

Package Outline Dimensions

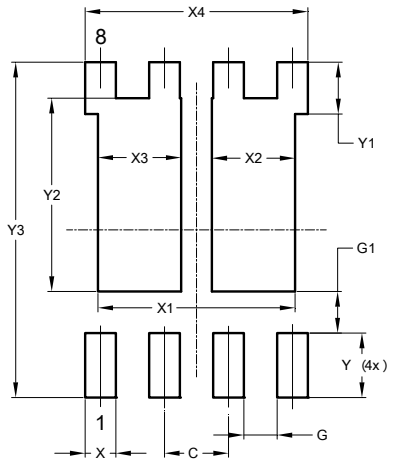
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



PowerDI5060-8			
Dim	**Min**	**Max**	**Typ**
A	0.90	1.10	1.00
A1	0	0.05	0.02
b	0.33	0.51	0.41
b1	0.300	0.366	0.333
b2	0.20	0.35	0.25
c	0.23	0.33	0.277
D	5.15 BSC		
D1	4.85	4.95	4.90
D2	1.40	1.60	1.50
D3	-	-	3.98
E	6.15 BSC		
E1	5.75	5.85	5.80
E2	3.56	3.76	3.66
e	1.27BSC		
k	-	-	1.27
k1	0.56	-	-
L	0.51	0.71	0.61
La	0.51	0.71	0.61
L1	0.05	0.20	0.175
L4	-	-	0.125
M	3.50	3.71	3.605
x	-	-	1.400
y	-	-	1.900
θ	10°	12°	11°
θ1	6°	8°	7°
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	0.610
X1	3.910
X2	1.650
X3	1.650
X4	4.420
Y	1.270
Y1	1.020
Y2	3.810
Y3	6.610

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1. are intended to implant into the body, or

2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

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